



PIN ASSIGNMENT MATRIX

	1	2
A	V_{CC}	GND
B	SCL	SDA

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	TYP	MAX	NOTE
A	0.260	0.295	0.330	
A1	—	0.070	—	
A2	—	0.225	—	3
D	Contact Microchip for Details			
d1	0.400 BSC			
E	Contact Microchip for Details			
e1	0.400 BSC			
b	—	0.162	—	

- Note: 1. Dimensions are NOT to scale.
 2. Solder ball composition is 95.5Sn-4.0Ag-0.5Cu.
 3. Product offered with Back Side Coating (BSC)

10/1/15

TITLE 4U-13, 4-ball 2x2 Array, 0.40mm Pitch Wafer Level Chip Scale Package (WLCSPP) with BSC	GPC GUJ	DRAWING NO. 4U-13	REV. A
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